

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2023/0230904 A1 **SHINSAI**

Jul. 20, 2023 (43) **Pub. Date:**

(54) **SEMICONDUCTOR DEVICE**

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Appl. No.: 18/095,603 (21)

(22)Filed: Jan. 11, 2023

(30)Foreign Application Priority Data

Jan. 17, 2022 (JP) 2022-004995

Publication Classification

(51) **Int. Cl.**

H01L 23/495 (2006.01)

H01L 23/31 (2006.01) H01L 23/00 (2006.01)(2006.01)H01L 25/16

U.S. Cl.

CPC H01L 23/49548 (2013.01); H01L 23/3121 (2013.01); H01L 24/48 (2013.01); H01L 25/16 (2013.01); H01L 2224/48175 (2013.01); H01L 2224/48141 (2013.01)

ABSTRACT (57)

A semiconductor device includes a base having a first surface on which the semiconductor element is mounted and a second surface opposite to the first surface, a first edge portion having a step from the first surface toward the second surface in a first region of a peripheral edge of the base, a first terminal that is arranged at a position facing the first edge portion when viewed from a thickness direction of the base, a conductive member for electrically connecting the semiconductor element and the first terminal to each other, and a resin material for sealing a part of the base, the semiconductor element, and a part of the first terminal.

